



Honeywell Ref. No.: H0001609
Attny Dkt. No. 100665.022US1

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ORIGINALLY FILED

Art Unit: 2827
Examiner: Cuneo, Kamand
Serial No.: 09/752,538
Inventor: Ohr, Stephen

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T. BELL.
6/13/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231

Inventor: **Ohr, Stephen**
Serial No: **09/752,538**
Filed: **December 28, 2000**
For: **Layered Circuit Boards
And Methods Of
Production Thereof**

Examiner: Cuneo, Kamand
Art Unit: 2827
Client Ref. No.: H0001609 (4960)
Attorney Docket No.: 100665.022US1

RESPONSE TO OFFICE ACTION

The Honorable Commissioner
of Patents and Trademarks
Washington, D.C. 20231

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Dear Sir:

This paper responds to the Office Action dated February 27, 2002. Please enter the following:

IN THE CLAIMS ✓

Cancel claims 10-18.

-
19. (Added) A sublamination layer, comprising:
- a single layer etched reference plane having a top surface and a bottom surface, the reference plain being formed by simultaneously etching both sides of a single layer of material;
 - a first signal layer coupled to the top surface with a first bond-ply material;
 - a second signal layer coupled to the bottom surface with a second bond-ply material; and
 - at least one of a through via.

20. (Added) The sublamination layer of claim 19 wherein the reference plane is thicker than either the first signal layer or the second signal layer.

IN THE DRAWINGS

A single page of replacement figures accompanies this transmittal. Please supplement the figures 1-4 on the accompanying page for figures 1-4 as filed.

REMARKS

Added Claims

Claims 19 and 20 were added, but no new matter was introduced. Claim 19 recites the same elements as claim 1 as filed, and also recites "the reference plain being formed by simultaneously etching both sides of a single layer of material". Support for this recitation can be found on page 6, lines 5-11 of the specification as filed. Claim 20 adds the recitation that "the reference plane is thicker than either the first signal layer or the second signal layer". Support for this recitation is found on page 5, lines 27-30.

Drawing Objections

The drawings were objected to for various reasons. Such rejections are moot in light of the drawing amendments proposed herein.

35 USC § 102

Claims 1-4 and 7-9 were rejected under 35 USC § 102(b) as being anticipated by Wiley (US4854038). The applicant disagrees as Wiley does not teach a sublamination layer as claimed in claims 1-4 and 7-9.

In particular, claim 1 recites an "etched" reference plane. Copper sheet 2 of Wiley, which the Office asserts qualifies as the claimed reference plane, is formed by drilling, not etching (see column 3, lines 21-23). As such, copper sheet 2 is not an etched reference plane, and Wiley does not anticipate any of claims 1-4 or 7-9.

35 USC § 103

Claims 6-7 were rejected under 35 USC § 103 as being obvious over Wiley. The applicant disagrees. Among other things, claims 6-7 are all allowable as being dependent upon allowable claims.

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ATTACHED MARKED-UP VERSION OF CHANGES

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "VERSION WITH MARKINGS TO SHOW CHANGES MADE".

REQUEST FOR ALLOWANCE

Claims 1-9 and 19-20 are pending in this application. The applicant requests allowance of all pending claims.

Respectfully submitted,

Rutan & Tucker, LLP

Dated: May 16, 2002

By: 

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